REMARKS/ARGUMENTS

Favorable reconsideration of this application is respectfully requested.

Claims 1, 2, and 9-21 are pending in this application. Claim 21 is added by the present response. Claims 3-8 are canceled by the present response without prejudice. Claims 1-20 were rejected under 35 U.S.C. § 103(a) as unpatentable over applicants' admitted art in view of U.S. patent 6,297,551 to <u>Dudderar et al.</u> (herein "Dudderar").

Addressing now the rejection of claims 1-20 under 35 U.S.C. § 103(a) as unpatentable over applicants' admitted art and <u>Dudderar</u>, that rejection is traversed by the present response.

First, with respect to independent claim 1, independent claim 1 is amended to clarify features recited therein. Specifically, independent claim 1 now includes certain features from dependent claims 3-8. The further features of the "protective film" and specifics of the "electrode structure" and of the "metal plating layer" now clarified in claim 1 are believed to distinguish over the applied art.

Further, with respect to each of the claims, applicants note each of independent claims 1, 9, and 15 is believed to recite a specific structure of an electrode structure including a first electrode layer and a metal plating layer which is not disclosed in the admitted art in view of Dudderar.

In the admitted art, for example in Figure 7, an electrode 97 is provided. As shown for example in Figure 7 no metal plating layer is formed on top of that electrode 97.

According to the claimed features, and with reference to Figure 1 of the present specification as a non-limiting example, a first electrode layer 17 is provided

and a metal plating layer 37 is provided on the first electrode layer. Such a structure is believed to clearly distinguish over the applied art.

The outstanding Office Action recognizes that the admitted art does not disclose a metal plating layer, and to overcome such deficiencies in the admitted art the outstanding Office Action cites <u>Dudderar</u> particularly at column 5, lines 4-47. In that respect, applicants note at that portion <u>Dudderar</u> discloses the use of a metal layer 21. As shown for example in the figures in <u>Dudderar</u> that metal layer 21 is formed on top of substrates 14, 62. Thus, <u>Dudderar</u> discloses at most forming a metal layer on top of a substrate. However, the claims require a different structure. More particularly, in the claims an electrode structure includes a first electrode layer and a metal plating layer on the first electrode layer. Again with reference to Figure 1 of the present specification as a non-limiting example a metal plating layer 37 is formed on the electrode 17. Clearly <u>Dudderar</u> does not teach or suggest such a structure. That is, <u>Dudderar</u> does not disclose or suggest forming any type of metal plating layer on an electrode structure.

Thus, <u>Dudderar</u> at most teaches putting a metal plating layer on top of a substrate. As that is the teaching that <u>Dudderar</u> provides, if the teachings in <u>Dudderar</u> of the metal layer 21 were combined with the teachings in the admitted art, that would clearly result in the admitted art being modified to include a metal layer on top of a substrate. Such a structure would not meet the claim limitations.

The claims recite an electrode structure including a first electrode layer and a metal plating layer on the first electrode layer, which clearly distinguishes over any combination of teachings of <u>Dudderar</u> in view of the admitted art.

Further, independent claims 9 and 15 are also amended by the present response to clarify the lead terminal being electrically connected to the first electrode

Application No. 10/020,928 Reply to Office Action of March 3, 2005

layer. That feature is believed to also neither be taught nor suggested by the admitted art or Dudderar.

In such ways, the claims as currently written are believed to distinguish over the combination of teachings of the admitted art in view of <u>Dudderar</u>.

As no other issues are pending in this application, it is respectfully submitted that the present application is now in condition for allowance, and it is hereby respectfully requested that this case be passed to issue.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

burch Sochos

Customer Number 22850

Tel: (703) 413-3000 Fax: (703) 413 -2220

(OSMMN 06/04)

I:\ATTY\SNS\21'\$\217636\217636US-AM 7-1-05.DOC

Eckhard H. Kuesters Registration No. 28,870 Surinder Sachar Registration No. 34,423 Attorneys of Record